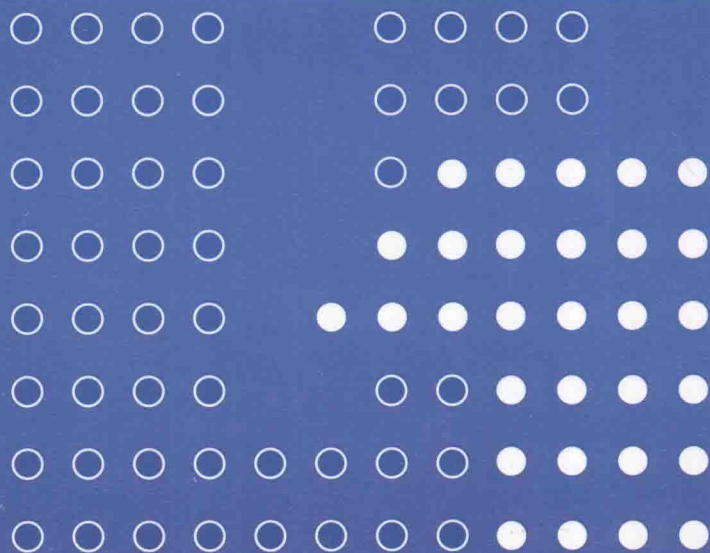
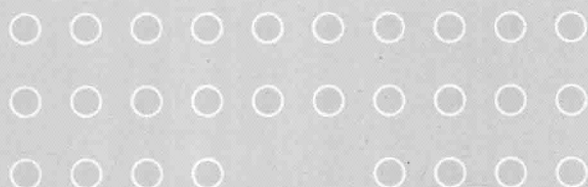
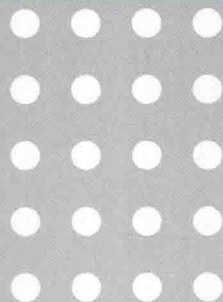


计算机系列教材

计算机新技术教程



汤晓兵 徐遵义 主 编
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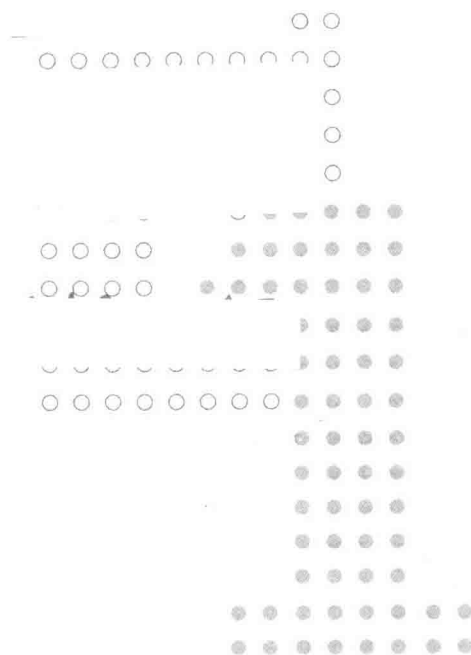
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内 容 简 介

本书精选和提炼了目前计算机专业领域最新的研究成果和学术进展,内容取材广泛,难易适中,每单元各具特色。通过对文章中专业词汇、语法结构的介绍和分析,为读者将来在信息技术以及相关研究方向的英文资料的阅读、翻译和写作等能力提供了重要的支撑和保证。本书结合作者多年计算机教学和科研中的宝贵经验,以及与国外学术交流的体会总结,在保证本书专业知识领先的同时,更着重体现了内容的实用性和针对性。读者在提高专业英语读、写、译水平的同时,可通过本书及时地跟踪 IT 领域内的顶尖技术,把握学术上的研究热点,确立未来的学习和科研方向。

本书面向的读者是高校信息技术相关专业的本科生、大专生或是从事软、硬件开发及相关领域的工程技术人员,通过对每个单元中英文文献专题的引入、分析和解决问题的过程,培养和提高读者在专业英语方面的阅读、翻译和写作的综合能力。

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本书在学习目标上有两个方面：一是从语言的角度来进行文章中英语的学习；二是对计算机专业领域相关知识的介绍，后者涵盖了从计算机的基本硬件和软件系统组成到计算机发展的前沿技术。在具体实施中，通过对这两个方面的交互渗透，在学好英语语义、语法的同时，让读者学习不同研究方向的计算机专业文献，对知识进行综合的学习和掌握，培养和提高读者在英文阅读、写作和翻译三个方面的专业英语综合学习和工作能力。

本书共分 12 个单元：第 1 单元硬件基础(Hardware)，第 2 单元软件基础(Software)，第 3 单元数据库(Database)为汤晓兵副教授编写，第 4 单元程序设计(Programming)，第 5 单元办公计算(Office Computing)，第 6 单元计算机网络(Networking)为徐遵义副教授编写，第 7 单元移动设备计算(Mobile Application)为赵洪鑫副教授编写，第 8 单元网络开发(Web Development)为袁卫华讲师编写，第 9 单元计算机安全(Security)为王庆东高级工程师编写，第 10 单元网络服务(Web Services)为詹玲讲师编写，第 11 单元大数据(Big Data)为白彧助理研究员编写，第 12 单元云计算(Cloud Computing)为康喆讲师编写。汤晓兵、袁卫华和徐晓静编写了每单元后针对词汇、语法结构和单元综述的测试与练习。汤晓兵负责全书的统稿。

在本书的编写过程中，得到了清华大学出版社的编辑以及刘祥昭老师的大力支持和帮助，在此对他们表示由衷的感谢。同时，感谢我的父母、妻子和双胞胎儿子们。在我编辑忙碌的时候，是他们的关心和爱护，支持着我集中精力、全力以赴地把书稿顺利完成。

由于编者水平有限，书中的缺点和不足难免，恳请读者指正。

编 者

F O R E W O R D

Unit 1 Hardware—Microwave Integrated Circuits /1

- 1.1 Classification of Microwave Integrated Circuits /1
- 1.2 Microwave Circuits in a Communication System /6
- 1.3 Summary /9
- 1.4 New Words and Expressions /10
- 1.5 Questions /10
- 1.6 Problems /12

Unit 2 Software—Microsoft Project 2013 and the Project Management Domain /13

- 2.1 History of Project Management /13
- 2.2 Exploring Project Management Industry Standards /14
 - 2.2.1 Project Management Body of Knowledge (PMBOK) /14
 - 2.2.2 PRINCE2 /18
- 2.3 WBS, Phases and Control Points, Methodologies, and Life Cycles /20
 - 2.3.1 Work Breakdown Structure(WBS) /20
 - 2.3.2 Managerial Control /21
 - 2.3.3 Phases and Gates /21
 - 2.3.4 Methodologies /22
 - 2.3.5 Life Cycles /22
- 2.4 Using Microsoft Project with Methodologies and Life Cycles /22
 - 2.4.1 Waterfall Development Process /23
 - 2.4.2 Iterative Development /23
 - 2.4.3 Research Project /27

2.5	Accommodating Teaming Styles	/27
2.6	Consultants' Tips	/28
2.6.1	Determine the Approach to Use in Managing Your Project	/28
2.6.2	Use WBS as a First Step in Project Definition	/28
2.6.3	Use the 5×9 Checklist for Planning	/29
2.7	New Words and Expressions	/29
2.8	Questions	/30
2.9	Problems	/31

Unit 3 Database—NoSQL Databases: An Overview /32

3.1	NoSQL: What does it mean	/32
3.2	Why NoSQL Databases	/32
3.3	Aggregate Data Models	/33
3.4	Distribution Models	/34
3.5	CAP theorem	/35
3.6	Types of NoSQL Databases	/36
3.6.1	Key-Value databases	/36
3.6.2	Document databases	/37
3.6.3	Column family stores	/38
3.6.4	Graph Databases	/38
3.7	Why choose NoSQL database	/40
3.8	Choosing NoSQL database	/41
3.9	Schema-less ramifications	/41
3.10	Conclusion	/42
3.11	New Words and Expressions	/42
3.12	Questions	/42
3.13	Problems	/45

Unit 4 Programming—What Software Architects Need to Know About DevOps /46

- 4.1 What Software Architects Need to Know About DevOps /46
- 4.2 Defining DevOps /46
- 4.3 DevOps Practices and Architectural Implications /48
- 4.4 Organizational Aspects of DevOps /50
- 4.5 Implications for Software Architecture: Microservices /51
- 4.6 Summary /52
- 4.7 New Words and Expressions /53
- 4.8 Questions /53
- 4.9 Problems /56

Unit 5 Office Computing—The Ultimate Player's Guide to Minecraft-Xbox Edition: Gathering Resources /57

- 5.1 Introducing the HUD /57
- 5.2 Avoiding Getting Lost /60
- 5.3 Improving Your Tools /61
- 5.4 Chests: Safely Stashing Your Stuff /63
- 5.5 Avoiding Monsters /64
- 5.6 Hunger Management /66
- 5.7 Your Mission: Food, Resources, and Reconnaissance /67
 - 5.7.1 Food on the Run /68
 - 5.7.2 Finding a Building Site /70
- 5.8 A Resourceful Guide to the Creative Mode Inventory /72
- 5.9 The Bottom Line /74
- 5.10 New Words and Expressions /74
- 5.11 Questions /75
- 5.12 Problems /77

Unit 6 Networking—Troubleshooting Methods for Cisco IP Networks /78

- 6.1 Troubleshooting Principles /78
- 6.2 Structured Troubleshooting Approaches /81
 - 6.2.1 The Top-Down Troubleshooting Approach /83
 - 6.2.2 The Bottom-Up Troubleshooting Approach /84
 - 6.2.3 The Divide-and-Conquer Troubleshooting Approach /85
 - 6.2.4 The Follow-the-Path Troubleshooting Approach /86
 - 6.2.5 The Compare-Configurations Troubleshooting Approach /87
 - 6.2.6 The Swap-Components Troubleshooting Approach /88
- 6.3 Troubleshooting Example Using Six Different Approaches /89
- 6.4 Summary /91
- 6.5 New Words and Expressions /91
- 6.6 Questions /92
- 6.7 Problems /94

Unit 7 Mobile Application—What's Special about Mobile Testing? /95

- 7.1 User Expectations /96
- 7.2 Mobility and Data Networks /97
- 7.3 Mobile Devices /98
- 7.4 Mobile Release Cycles /100
- 7.5 Mobile Testing Is Software Testing /101
- 7.6 Summary /102
- 7.7 New Words and Expressions /102

7.8 Questions /103

7.9 Problems /105

**Unit 8 Web Development—The Mobile Commerce Revolution
and the Current State of Mobile /106**

8.1 Americans and Smartphones /106

8.2 Mobile Around the World /109

8.3 Mobile Commerce /110

8.4 Beyond the Numbers /110

8.5 The Bottom Line /113

8.6 New Words and Expressions /113

8.7 Questions /114

8.8 Problems /116

**Unit 9 Security—Information Security Principles of
Success /117**

9.1 Introduction /117

9.2 Principle 1: There Is No Such Thing As Absolute
Security /117

9.3 Principle 2: The Three Security Goals Are
Confidentiality, Integrity, and Availability /119

9.3.1 Integrity Models /119

9.3.2 Availability Models /120

9.4 Principle 3: Defense in Depth as Strategy /120

9.5 Principle 4: When Left on Their Own, People
Tend to Make the Worst Security Decisions /122

9.6 Principle 5: Computer Security Depends on Two
Types of Requirements: Functional and
Assurance /122

9.7 Principle 6: Security Through Obscurity Is Not
an Answer /123

9.8 Principle 7: Security = Risk Management /124

- 9.9 Principle 8: The Three Types of Security Controls Are Preventative, Detective, and Responsive /126
- 9.10 Principle 9: Complexity Is the Enemy of Security /127
- 9.11 Principle 10: Fear, Uncertainty, and Doubt Do Not Work in Selling Security /127
- 9.12 Principle 11: People, Process, and Technology Are All Needed to Adequately Secure a System or Facility /127
- 9.13 Principle 12: Open Disclosure of Vulnerabilities Is Good for Security! /128
- 9.14 Summary /129
- 9.15 New Words and Expressions /129
- 9.16 Questions /130
- 9.17 Problems /131

Unit 10 Web Services—Designing Software in a Distributed World /132

- 10.1 Visibility at Scale /133
- 10.2 The Importance of Simplicity /134
- 10.3 Composition /134
 - 10.3.1 Load Balancer with Multiple Backend Replicas /134
 - 10.3.2 Server with Multiple Backends /136
 - 10.3.3 Server Tree /138
- 10.4 Distributed State /139
- 10.5 The CAP Principle /142
 - 10.5.1 Consistency /142
 - 10.5.2 Availability /143
 - 10.5.3 Partition Tolerance /143
- 10.6 Loosely Coupled Systems /145

- 10.7 Speed /147
- 10.8 Summary /150
- 10.9 New Words and Expressions /151
- 10.10 Questions /151
- 10.11 Problems /153

Unit 11 Big Data—Big Data Computing /154

- 11.1 Introduction /154
- 11.2 Apache Hadoop Data modelling /156
- 11.3 NoSQL Big Data systems /157
 - 11.3.1 Key Value stores /157
 - 11.3.2 Document databases /157
 - 11.3.3 Graph databases /158
 - 11.3.4 XML databases /158
 - 11.3.5 Distributed Peer Stores /158
 - 11.3.6 Object stores /159
- 11.4 Definitions of Data Management /159
 - 11.4.1 Data management /159
 - 11.4.2 Big data management (BDM) /160
- 11.5 The State of Big Data Management /160
- 11.6 Big Data Tools /162
 - 11.6.1 Big data tools: Jaspersoft BI Suite /162
 - 11.6.2 Big data tools: Pentaho Business Analytics /163
 - 11.6.3 Big data tools: Karmasphere Studio and Analyst /163
 - 11.6.4 Big data tools: Talend Open Studio /164
 - 11.6.5 Big data tools: Skytree Server /164
 - 11.6.6 Big data tools: Tableau Desktop and Server /165
 - 11.6.7 Big data tools: Splunk /165
- 11.7 New Words and Expressions /166

11.8 Questions /166

11.9 Problems /168

**Unit 12 Cloud Computing—The Practice of Cloud
System Administration: Operations in a
Distributed World /169**

12.1 Distributed Systems Operations /170

12.1.1 SRE versus Traditional Enterprise
IT /170

12.1.2 Change versus Stability /171

12.1.3 Defining SRE /173

12.1.4 Operations at Scale /174

12.2 Service Life Cycle /177

12.2.1 Service Launches /178

12.2.2 Service Decommissioning /180

12.3 Organizing Strategy for Operational Teams /180

12.3.1 Team Member Day Types /183

12.3.2 Other Strategies /185

12.4 Virtual Office /186

12.4.1 Communication Mechanisms /187

12.4.2 Communication Policies /187

12.5 Summary /188

12.6 New Words and Expressions /189

12.7 Questions /190

12.8 Problems /191

Answers to Questions /193

References /194

Unit 1 Hardware—Microwave Integrated Circuits

This chapter covers the following topics:

- 1.1 Classification of Microwave Integrated Circuits
- 1.2 Microwave Circuits in a Communication System
- 1.3 Summary

1.1 Classification of Microwave Integrated Circuits

An active microwave circuit can be defined as a circuit in which active and passive microwave devices such as resistors, capacitors, and inductors are interconnected by transmission lines. At low frequencies, the transmission lines are a simple connection; however, at microwave frequencies they are no longer just simple connections and their operation becomes a complicated distributed circuit element. As a result, a microwave integrated circuit's classification is based on the fabrication method of the transmission lines used for interconnection.

There are various types of transmission lines in microwave integrated circuits; some common examples are waveguides, coaxial, and microstrip lines. Figure 1.1 shows the transmission lines used in microwave circuits. Although there are special cases of microwave integrated circuits that are composed of coaxial lines and waveguides, in most cases the microwave integrated circuits are formed using planar transmission lines. Therefore, the content of this book is restricted to microwave integrated circuits formed using planar transmission lines, examples of which are microstrip, slot line, and co-planar waveguide (CPW), as shown in Figure 1.2. These planar transmission lines are frequently used in the large-scale production of microwave circuits and generally form the basic transmission lines for microwave circuits.

The implementation of planar transmission lines on substrates can be classified into two basic groups: *monolithic* and *hybrid integrated circuits*. In monolithic integration, the active and passive devices as well as the planar transmission lines are grown *in situ* on one planar substrate that is usually made from a semiconductor material called a wafer.

Figure 1.3 shows an example of monolithic integration. Figure 1.3(a) is a photograph of the top side of a wafer and Figure 1.3(b) shows a single monolithic

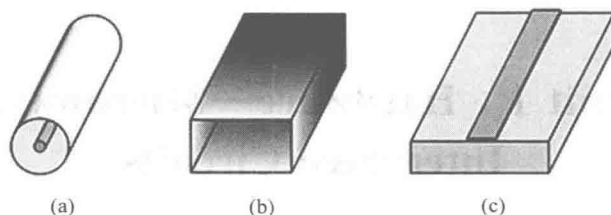


Figure 1.1 Some common transmission lines used in microwave circuits: (a) coaxial line, (b) rectangular waveguide, and (c) microstrip line.

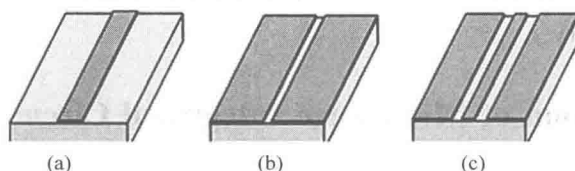


Figure 1.2 Some common planar transmission lines used in microwave circuits: (a) microstrip, (b) slot line, and (c) CPW (co-planar waveguide).

microwave integrated circuit; the identical circuits are repeatedly produced on the wafer in Figure 1.3(a). The monolithic microwave integrated circuit in Figure 1.3(b) is found to contain active and passive devices, and planar transmission lines. The monolithic integration provides a compact sized circuit and eliminates a significant amount of assembly when building a component or a system. Especially because size is of critical importance in most recent RF systems, monolithic integration is frequently employed to provide a compact component. An advantage of monolithic integration is that it is well suited for large-scale production, which results in lower costs. A disadvantage is that monolithic integration takes a long time to develop and fabricate, and small-scale production results in highly prohibitive costs.

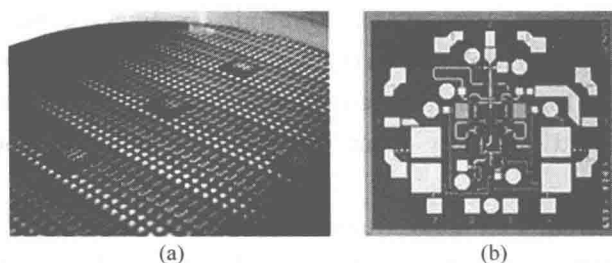


Figure 1.3 Monolithic integration: (a) a wafer and (b) a monolithic microwave integrated circuit on the wafer.

Hybrid integration is a fabrication method in which the transmission lines are implemented by conductor patterns on a selected substrate with either *printing* or

etching, and active and passive devices are assembled on the patterned substrate by either soldering or wire bonding. When implementing transmission lines by conductor patterns on a substrate, careful consideration must be given to the substrate material and the conductor material for the transmission lines because these materials can have significant effects on the characteristics of transmission lines. Hybrid integration is thus classified into three types based on the method by which the lines are formed on the substrate: a *printed circuit board* (PCB), a *thick-film* substrate, and a *thin-film* substrate.

Figure 1.4 shows an example of how connection lines are formed on a PCB substrate. Both sides of the dielectric material are attached with copper cladding that is then etched to obtain the desired conductor patterns. For PCB substrate materials, epoxy fiberglass (FR4), teflon, and duroid are widely used. FR4 substrate (a kind of epoxy fiberglass) can be used from lower frequencies to approximately 4 GHz, while teflon or duroid can be used up to the millimeter wave frequencies, depending on their formation. Generally, all these materials lend themselves to soldering while wire bonding for an integrated circuit assembly is typically not widely used. Furthermore, compared with other methods that will be explained later, a PCB can result in lower costs; its fabrication is easy and requires less time to produce. In addition, production on a small scale is possible without the use of expensive assembly machines; it is easy to fix and could also be used in large-scale production, and is thus widely used.

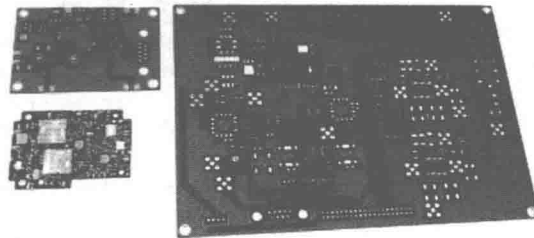


Figure 1.4 A photograph of epoxy fiberglass PCBs.

The PCBs on the left are for the X-band and 2 GHz frequency synthesizers using the phase locked loop. The PCB on the right is for the VHF automatic identification system, which has a similar block diagram shown in Figure 1.7. The power amplifier is implemented in a separate block.

Thick-film substrates are produced by screen-printing techniques in which conductor patterns are formed by pushing conductive paste on a ceramic substrate through a patterned screen and then firing printed conductor patterns. The substrate is called thick film because the patterns formed by such techniques are generally much thicker than those formed using thin-film techniques. As a benefit of using screen-

printing techniques, multiple screen printings are possible. Dielectric or resistor patterns can also be formed by similar screen-printing techniques using dielectric or resistor pastes. Using an appropriate order of multiple screen printings, it is also possible to form capacitors and resistors on the ceramic substrate. Since the ceramic substrate is more tolerant of heat, it is easy to assemble active devices in the form of chips. On the other hand, considering the lines and patterns formed by this process, the pattern accuracy of thick film is somewhat inferior compared to that of thin film. The costs and development time, on a case-by-case basis, are somewhere between those of the PCB and thin-film processes. Recently, however, the integration based on thick-film technology has become rare because its cost and pattern accuracy are between the PCB and thin-film technology, while thick film is widely used to build multifunction components. A typical example is the package based on LTCC (low-temperature co-fired ceramics) technology. Figure 1.5 Multilayer ceramics and structuring are possible in LTCC technologies. Figure 1.5 shows a photograph of thick-film patterned substrates fabricated using the thick-film process.

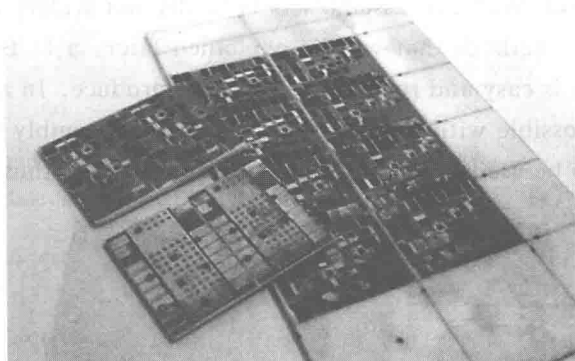


Figure 1.5 A photograph of substrates fabricated by the thick-film process.

The thin-film technique is very widely used in the fabrication of microwave circuits for military and microwave communication systems. In the case of the thin-film process, a similar ceramic substrate material used in thick film is employed, but compared to the thick-film substrate, a fine surface-finish substrate is used. The most widely used substrate is 99% alumina (Al_2O_3). Other substrates such as fused silica, quartz, and so on are possible for conductor-pattern generation based on thin-film technologies. The pattern formation on the substrate is created with a photolithographic process that can produce fine tracks of conductor patterns similar to those in a semiconductor process. Since the thin-film substrate is also alumina as in the case of a thick-film substrate, the assembly of semiconductor chips using wire bonding is possible. Thin film compared with PCB and thick film is more expensive, and due to the requirement of fine tracks, a mask fabrication is necessary and the process

generally takes longer. Passive components such as resistors and air-bridge capacitors can be implemented using this process. In addition, integrated circuits produced by the thin-film process require special wire bonders and microwelding equipment for assembly. Compared to the monolithic integration process, the thin-film process tends to be cheaper in terms of cost, but compared to MMIC, the assembled circuit using the thin-film patterned substrate is difficult to characterize precisely because of unknown or poorly described parasitic circuit elements associated with the assembly methods such as wire bonding and die attach. Before the emergence of MMICs (monolithic microwave integrated circuits), thin-film technology was the conventional method for building microwave-integrated circuits (MICs). Figure 1.6 is a photograph of thin-film circuits fabricated with the thin-film technique.

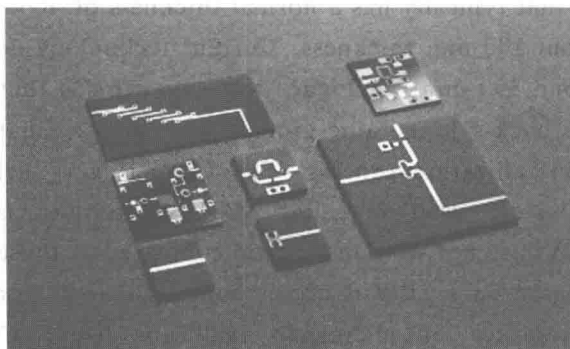


Figure 1.6 A photograph of substrates produced by the thin-film process.

From top left to bottom right, they are filter, phase shifter, power amplifier, path-switching circuit by assembly, power divider, and 50 Ω lines.

The choice of integration method depends on the application and situation, taking into account several factors mentioned previously, such as the operating frequency of the integrated circuit, the types of semiconductor components (chip or packaged), the forms of the passive components, large-scale fabrication costs, and method of assembly. These factors should all be considered when selecting the optimum method of integration. Table 1.1 provides a comparison of the hybrid integrations described previously.

Table 1.1 Comparison of hybrid integration

Technology	Cost	Fabrication Time	Pattern Accuracy	Assembly
PCB	Low	Short	Low	Soldering
Thick film	Middle	Middle	Low	Soldering and wire bonding
Thin film	High	Long	Fine	Soldering and wire bonding